Businesses & Products

Ceramic Surface-Mount Packages
Kyocera’s ultra-small ceramic surface-mount packages for crystal oscillators and other components help to miniaturize smart devices while enhancing their performance.

Ceramic Packages for Image Sensors
Ceramic packages for image sensors help create smaller camera modules with higher performance.

Optical Components
Kyocera supports today’s broadband Internet with components such as fiber-optic connectors and laser-diode packages that protect signal devices and ensure high data speeds.

Ceramic Packages for LEDs
The excellent thermal conductivity and reliability of Kyocera’s ceramics make them ideal for packaging LEDs used in applications ranging from residential lighting to vehicle headlamps.

Multilayer Ceramic Substrates for Automotive ECUs
Kyocera’s compact ECU substrates are used in automotive powertrain systems, where they provide high circuit density with excellent heat resistance, heat dissipation and reliability.

Ultra-Small Ceramic Packages Help Miniaturize Crystal Devices
Crystal devices are used in a wide range of electronic equipment. Kyocera’s ceramic packages enhance crystal performance in a condensed size. At right is a ceramic package measuring just 1.2 x 1mm. Multilayer ceramic technology allows designers to build internal wiring and a cavity structure within these tiny packages, protecting the device with hermetic sealing for high reliability.

Organic Packages & Printed Wiring Boards
The rapid advancement of information and communication technologies (ICT) and the expansion of the Internet demand electronic devices with better functionality and performance. Kyocera’s organic multilayer packages and printed wiring boards help meet this demand.

Flip-Chip Packages
These fine-pitch multilayer packages employ the latest advances in micro-wiring and low-profile multilayer technology. They support better functionality and performance in servers, routers and mobile communication devices.

Substrates for Wireless Communications
Kyocera’s organic substrates are used in telecommunications modules for smartphones and on-board automotive systems, where embedded capacitors and other components are required.

Build-up Wiring Boards
These wiring boards are widely used in PCs, mobile devices, and other products that employ high-density surface-mounted boards.

High-Density Multilayer Printed Circuit Boards
These high-performance circuit boards are used in high-end servers and telecommunications systems, where large-scale motherboards and backplane boards may require up to 50 layers.

Semiconductor Components

Ceramic Packages & Substrates
High-reliability ceramic packages and substrates help to miniaturize components used in smartphones, fiber optics, automotive electronics, headlight LEDs and a wide range of other products. Kyocera utilizes its broad expertise in materials, processing, and design technologies to ensure unparalleled substrate and package performance.

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